



Status of SRS + Timepix

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Outline



- Motivation
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- Timepix chip
- Status at testbeam 2013
- Status now
- Plans for 2014

Motivation

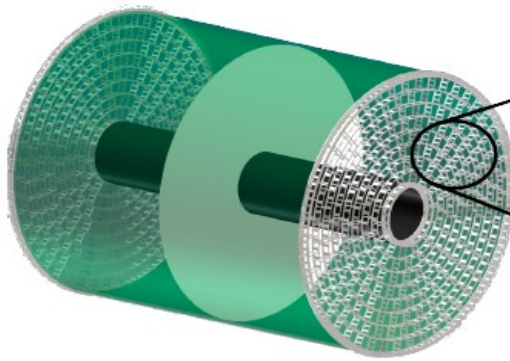


Goal: ~100 Chip module for the LCTPC prototype at DESY

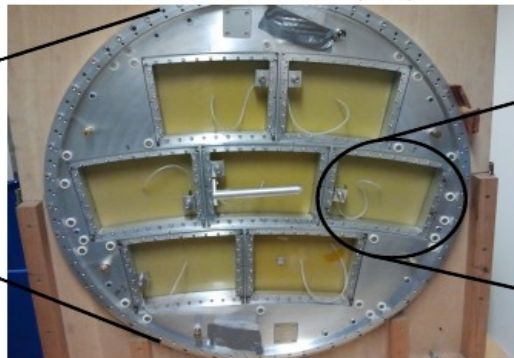
→ channels: $256 \times 256 \times 100 = 6,5$ mio

→ demonstrator module for a pixel TPC

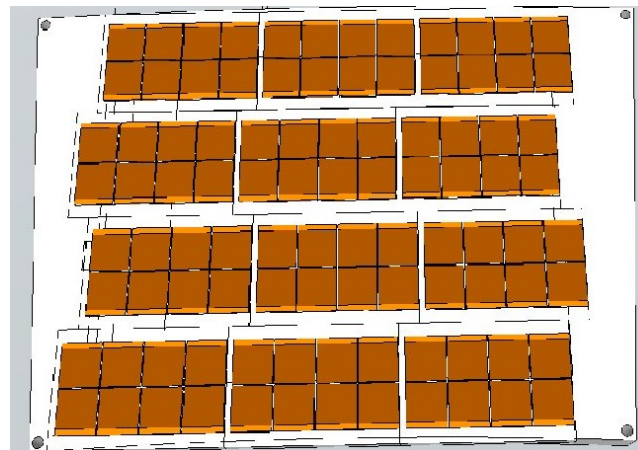
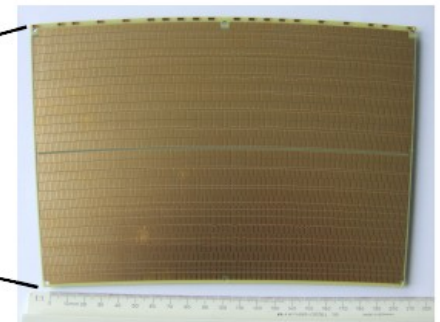
ILD TPC



Large Prototype (LP)



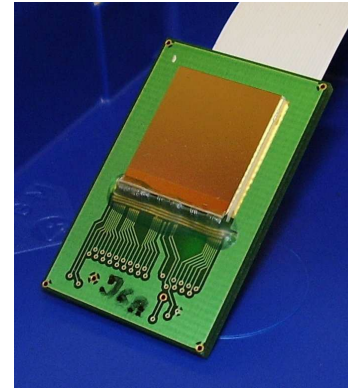
Trapezoid Readout Module
(230 mm × 170 mm)



Timepix chip

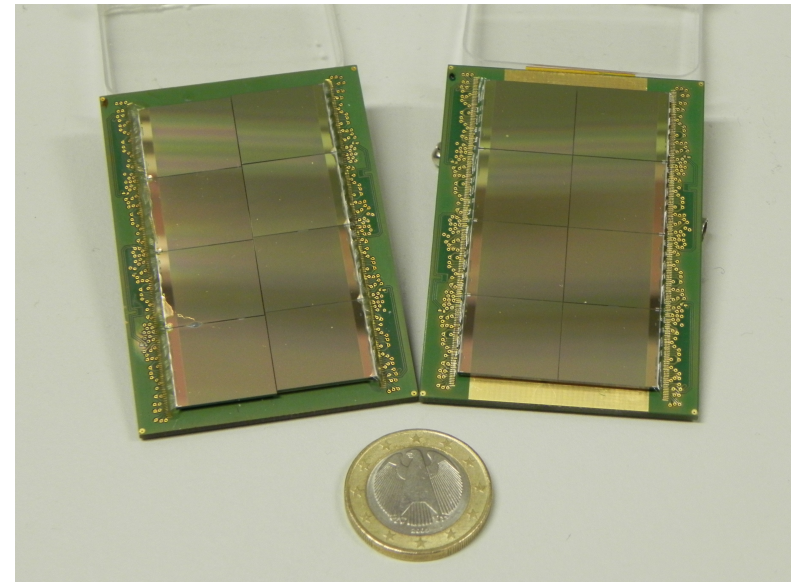


- Digital readout chip: The Timepix ASIC



- Properties

- 1.4 x 1.4 cm² active surface
- 256 x 256 pixel matrix
- CMOS 250 nm technology, IBM
- 55 x 55 μm² per pixel
- amplifier/shaper ($t_{\text{rise}} \sim 150$ ns)
- 14 bits count clock cycles
 - Pixel pit when/how long
- clock up to 100 MHz in every pixel
- lower threshold
- threshold level $\sim 500 e^-$ (90 e^- ENC)

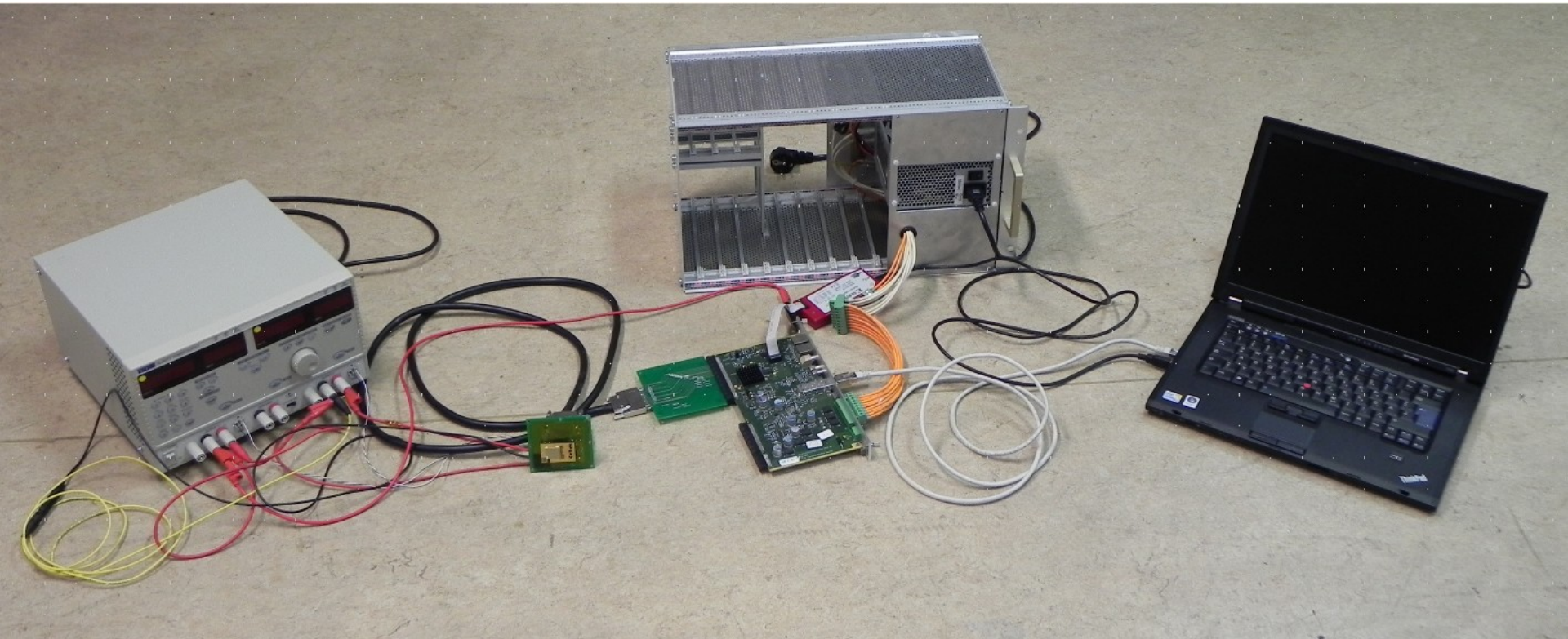


- Used as readout anode plane in gaseous detectors

Status at testbeam 2013



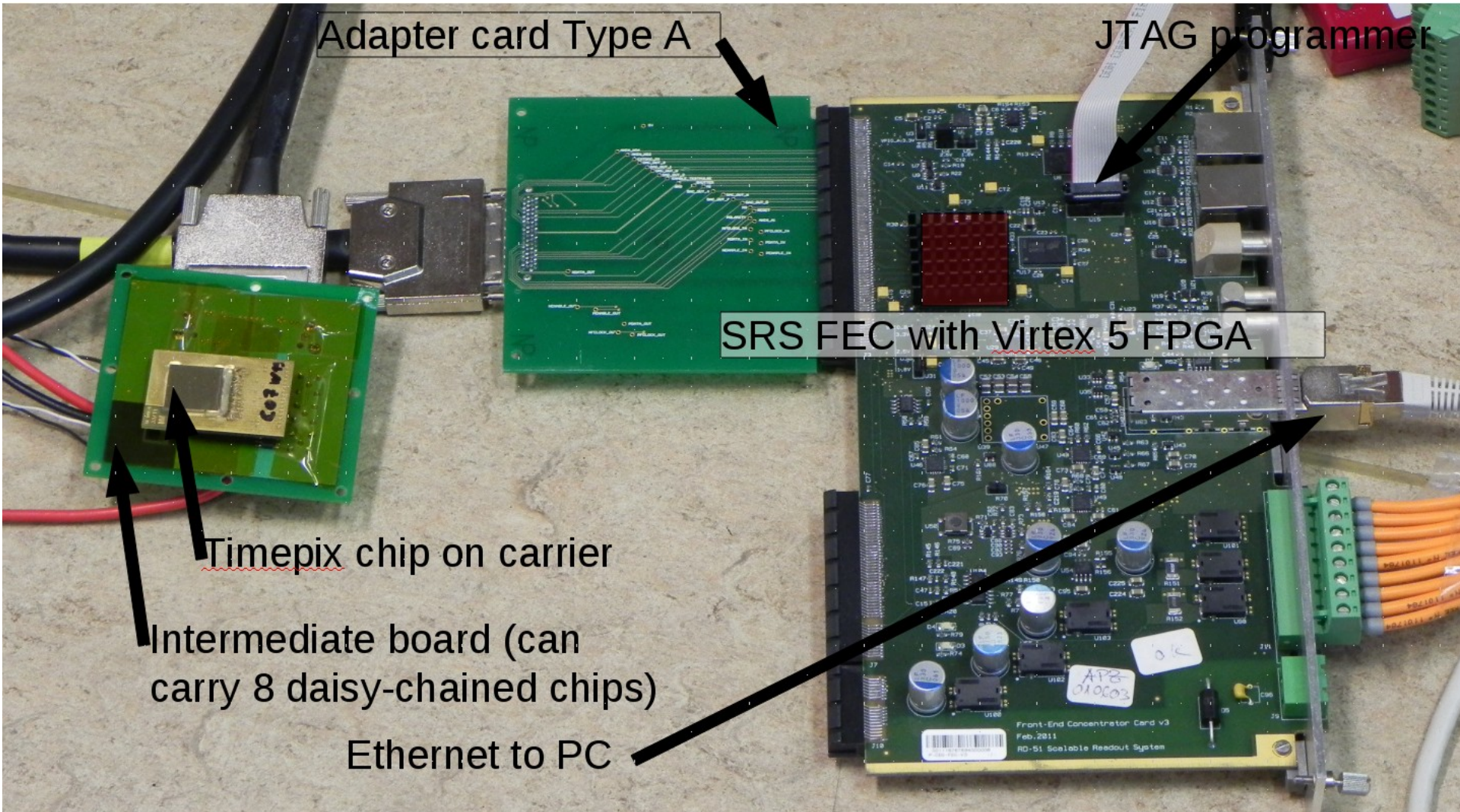
- 2 modules, each 8 chips (one InGrid, one triple GEM)
- Readout chain:



Status at testbeam 2013



- FEC and simple A Card:



Adapter card Type A

JTAG programmer

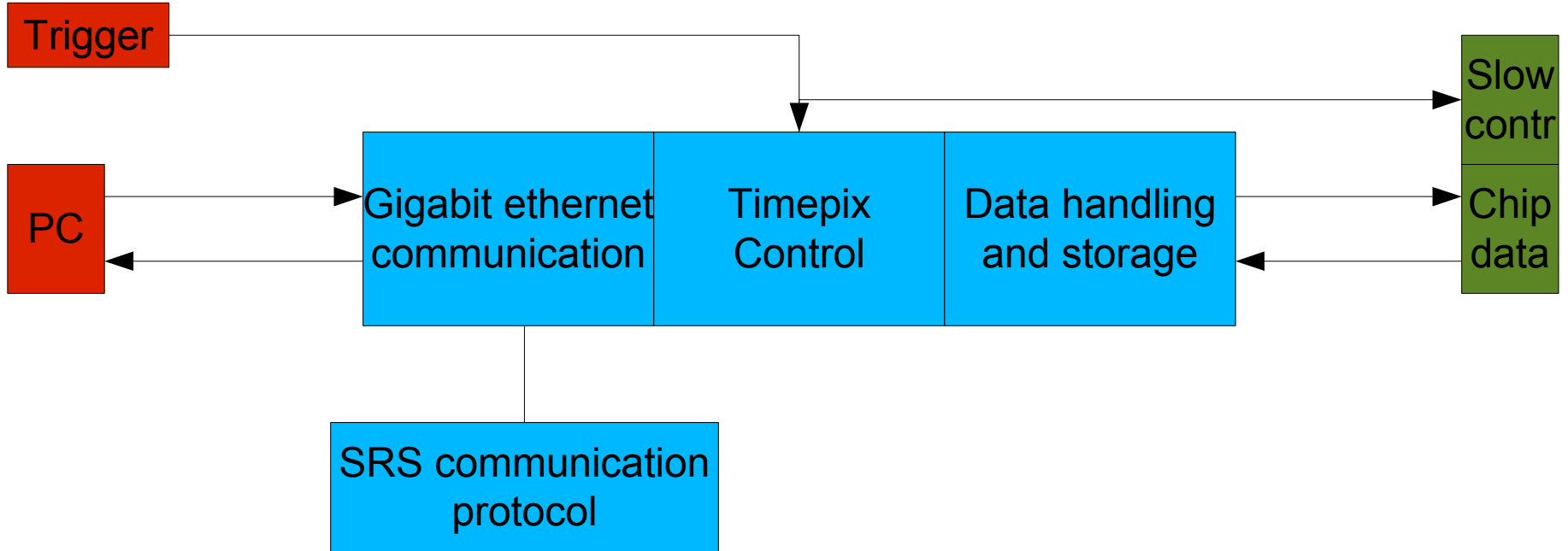
SRS FEC with Virtex 5 FPGA

Timepix chip on carrier

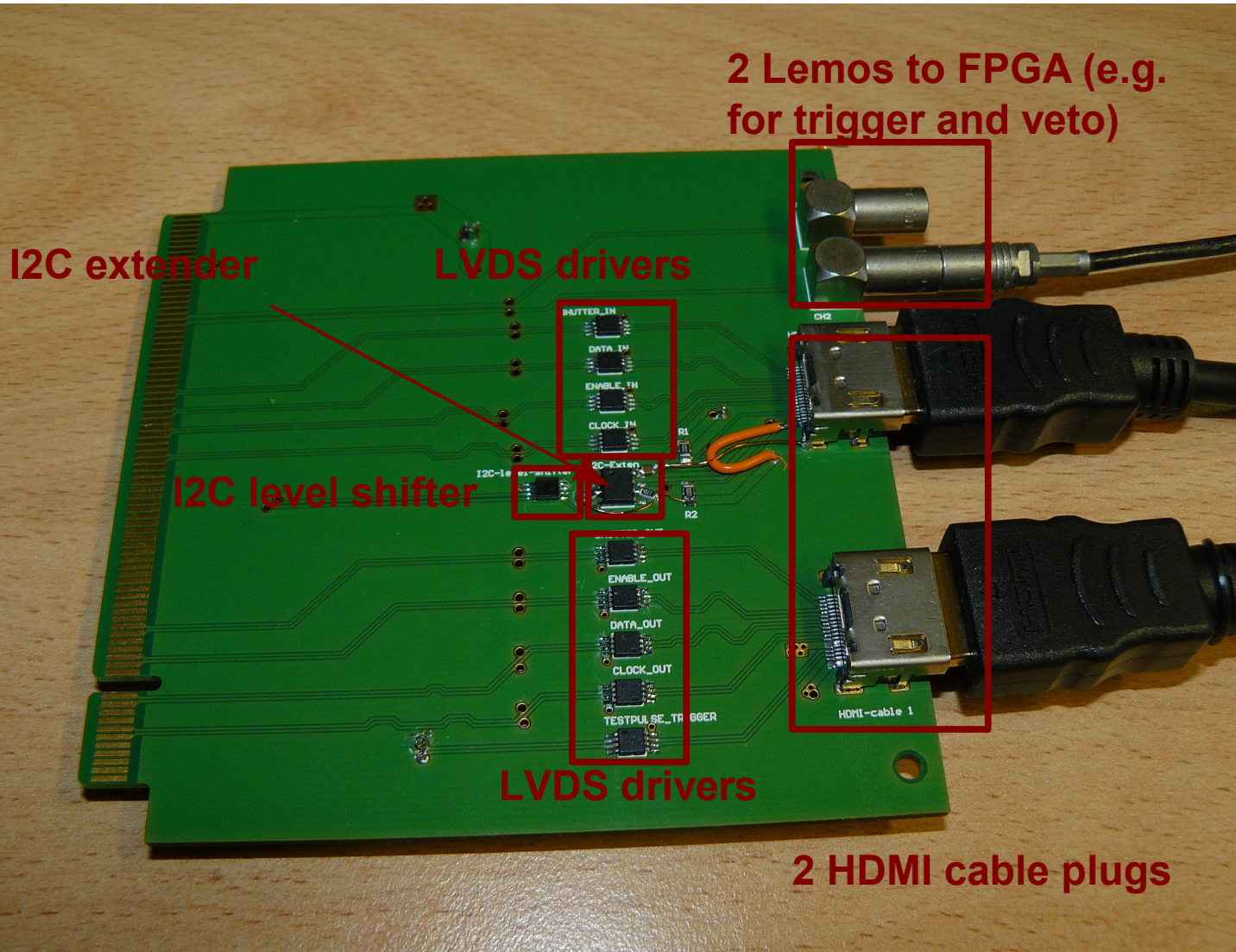
Intermediate board (can carry 8 daisy-chained chips)

Ethernet to PC

FPGA Firmware



New A Card

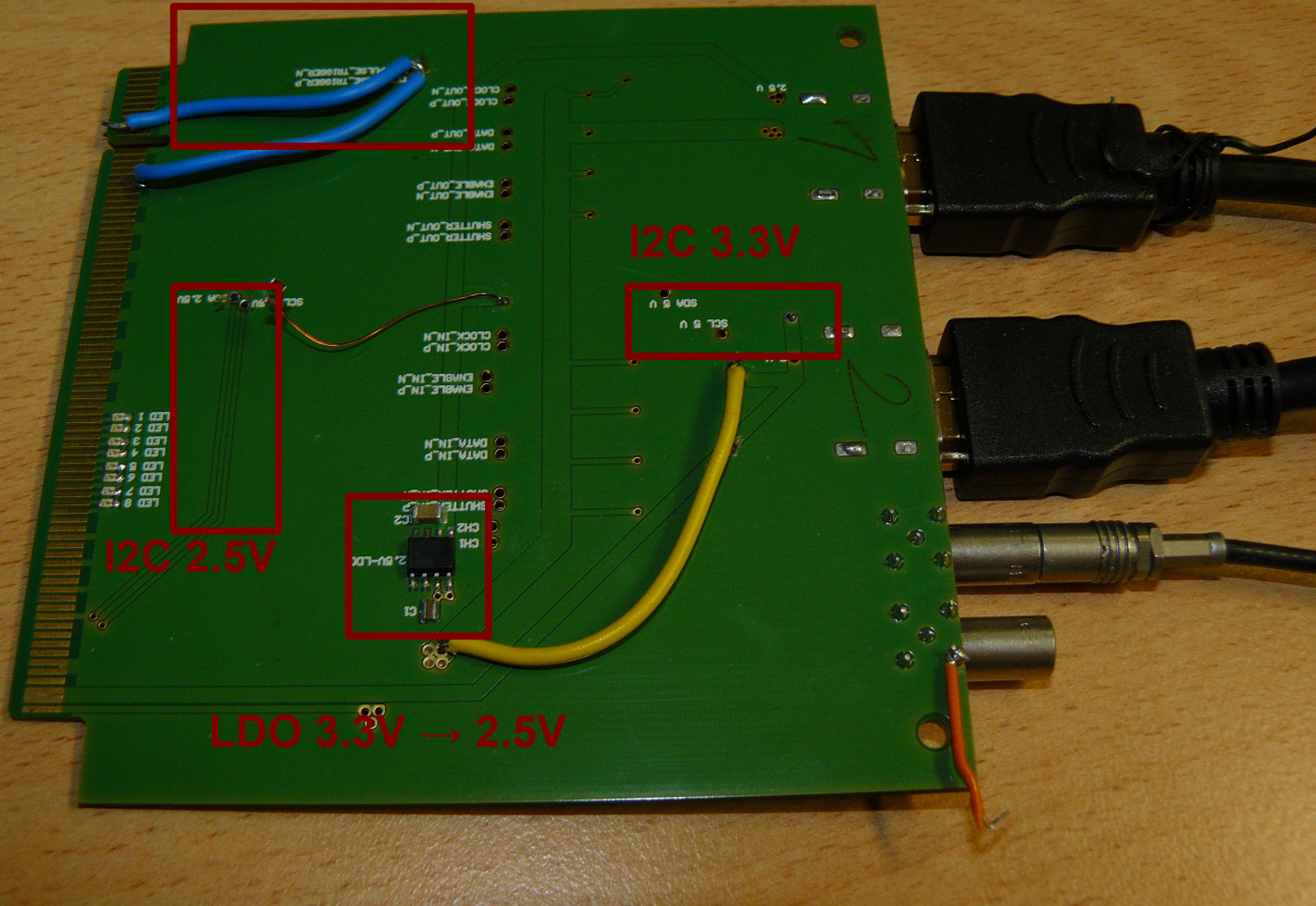


I2C: standard for small network.
Signals:
scl: clock
sda: data
Originally between PCBs next to each other.
With externs:
Several meters distance.

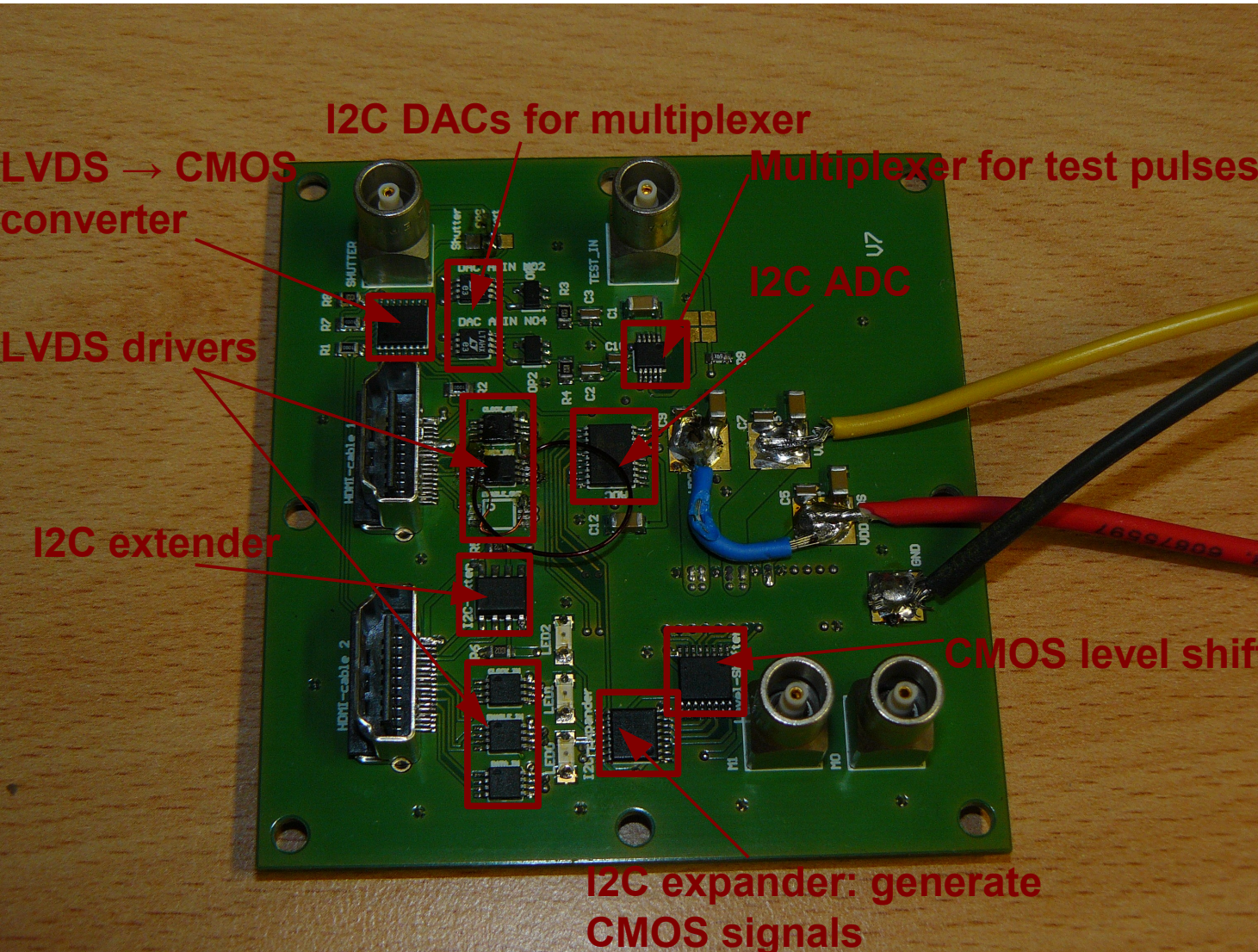
New A Card



Internal testpulse trigger

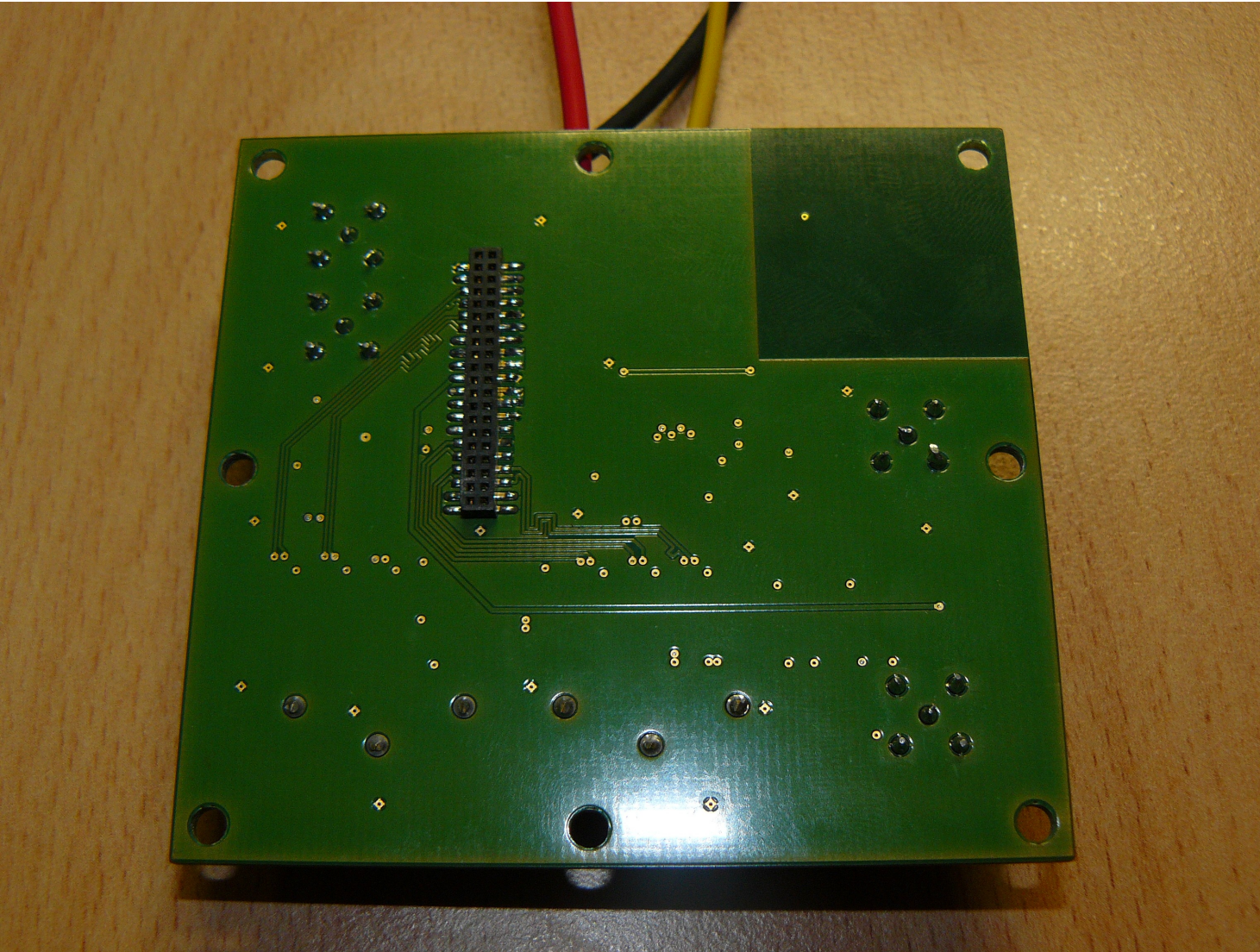


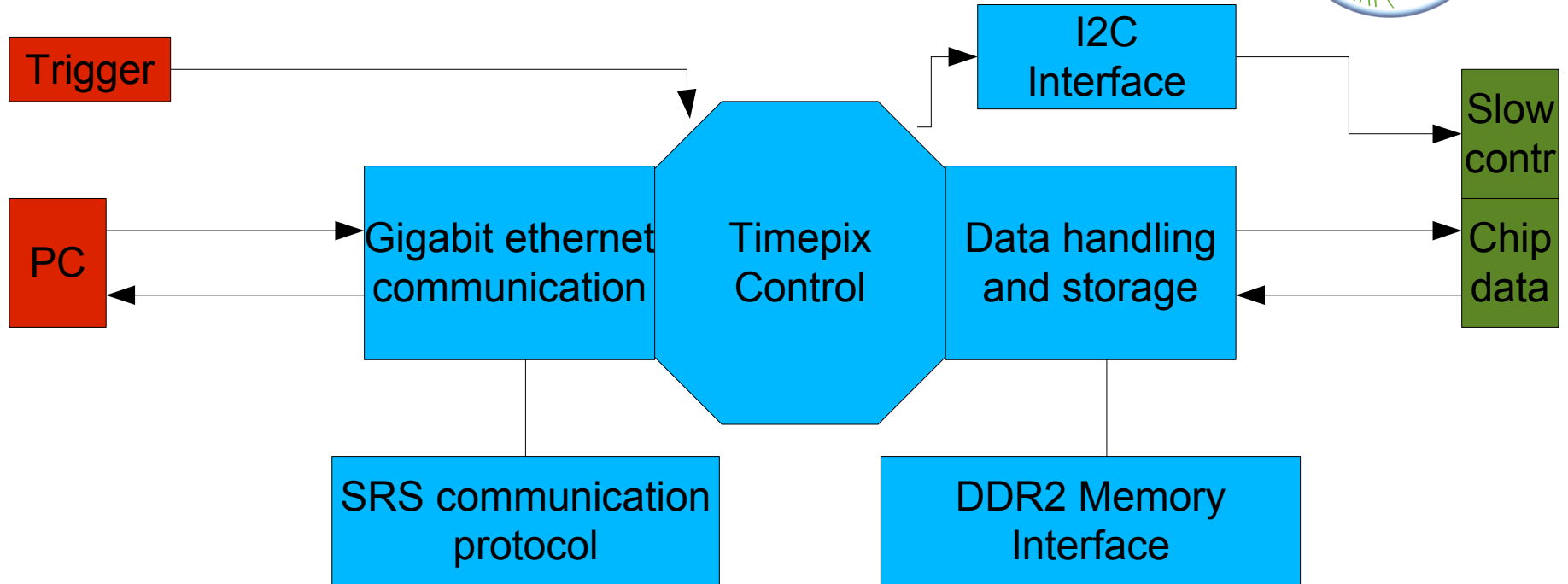
New Intermediate board



CMOS level shifter 2.5V → 2.2V

New Intermediate board





New features:

- ~~Multithreading~~ (read chip while sending data of last frame)
- DDR2 RAM to store data of 8 chips
- I2C for slow control

Status Timepix+SRS Readout



- New A-Card and intermediate board:
 - HDMI cables
 - Signals optimised for long distance (~25 m)
 - Many new components on A card and intermediate board:
 - LVDS drivers for long distance
 - I2C network for CMOS signal reduction
 - Remaining CMOS signals transmitted as LVDS and converted to CMOS on intermediate board
 - I2C level shifter and extender for long distance
 - ADC to read back analogue signals from Chip (DAC_out)
 - DACs to set voltages for multiplexer
- New parts of FPGA Firmware:
 - I2C Interface
 - DDR2 Interface

Status Timepix+SRS Readout



- Test of new components ongoing
 - I2C network ok (DACs, ADC, expander work)
 - DDR2 Ram ok, needs long time testing
 - LVDS driver work

=> chip can be operated, setting/reading matrix ok
data taking ok, even for 8 chips
- Test of FPGA Firmware:
 - DDR2 Ram ok, needs long time testing
 - I2C interface ready
- Software implementation coming (e.g. ADC readout, automatic calibration, ...)

Plans for 2014



- System for 96 chips
 - Get FECs with V6
 - 12 octoboards
 - 3 or 4 octoboards / FEC
 - => check PCI pinout
 - Synchronisation, trigger? Need CTF card?
- Module construction:
 - Space is limited
 - Electronics
 - Low voltage? 12 x 2,2V/4A power supply
 - HV for gas amplification
- Software
 - => go to testbeam at the end of 2014

We can provide soon:



- SRS (A card) with full functionality (for MUROS compatible intermediate board)
 - Users with SRS can plug and play Timepix
 - Users can use MUROS or SRS for same detector
 - Comparability study, documentation
- V6 evaluation board (VHDCI cables MUROS compatible):
 - Updated adapter board, I2c network tested
 - ADC, DAC control and readout with i2c (firmware, software)
 - Users with V6 board can plug and play Timepix
 - Users can use MUROS or SRS for same detector
 - Comparability study, documentation:
 - Use in CAST

Summary and Outlook



SRS + Timepix had a very successful 2013.

SRS + Timepix readout system got new hardware components optimised for test beam.

Preparation of LCTPC module with ~100 chips

- Scaling up of new hardware
- Want: 3-4 Octoboards/FEC
- Power supply still unsolved